

WHAT IS CLAIMED IS:

1. A copper-clad laminate comprising a polyimide
5 film and an electrolytically plated copper film placed on
at least one surface side of the polyimide film, in which
the electrolytically plated copper film has at most 200
protrusions having a diameter of 15 μm or more on a sur-
face thereof not facing the polyimide film, and the lami-
10 nate has a peel strength of 1 kgf/cm or more and shows a
peel strength of 0.6 kgf/cm or more after heating at 150°C
for 24 hours.

2. The copper-clad laminate of claim 1, in which
15 the copper-clad laminate has a continuous laminate having
a width of 540 mm or more and the copper film has such
uniform thickness in a width direction thereof that the
thickness varies within at most $\pm 10\%$ at least in a range
of 80% of the width.

20 3. The copper-clad laminate of claim 1, in which
the polyimide film has a surface facing the plated copper
film, which has protrusions arranged to form a network of
protrusions.

25 4. The copper-clad laminate of claim 1, in which
the polyimide film is prepared from a biphenyltetra-
carboxylic compound and a diamine compound comprising
4,4'-diaminodiphenyl ether.

30 5. The copper-clad laminate of claim 1, in which
the polyimide film comprises a high heat resistant aro-
matic polyimide core layer and a flexible aromatic poly-
imide surface layers, the latter flexible polyimide lay-
35 ers comprises polyimide having a flexible bonding in a
molecular structure thereof.

6. The copper-clad laminate of claim 1, in which at least two deposited metal layers are placed between the polyimide film and the plated copper film, and the plated copper film and the deposited metal layers have a
5 total thickness in the range of 1 to 20 μm .

7. The copper-clad laminate of claim 1, in which the polyimide film has the plated copper layer on one surface side thereof and a heat conductive deposited
10 metal or ceramic layer on another surface side thereof.

8. The copper-clad laminate of claim 1, in which the polyimide film has the plated copper layer on both surface side thereof.
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9. The copper-clad laminate of claim 1, which shows a peel strength of 0.6 kgf/cm or more after PCT processing which is performed at 121°C for 168 hours under the conditions of 2 atm. and RH 100%.
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10. The copper-clad laminate of claim 1, in which the plated copper layer has 0 to 200 protrusions per 1 mm^2 which have a diameter of 15 to 1,000 μm .

11. The copper-clad laminate of claim 1, in which the plated copper layer has 1 to 200 protrusions per 1 mm^2 which have a diameter of more than 15 μm .
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12. The copper-clad laminate of claim 1, in which the plated copper layer has 0 to 50 protrusions per 1 mm^2 which have a diameter of more than 15 μm .
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13. A process for preparing a copper-clad laminate of claim 1, comprising the steps of:
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preparing a polyimide film having a combination of metal deposited underlying layer and a copper-deposited

surface layer at least on one surface thereof; and
placing a copper film on the copper-deposited surface layer by electrolytically plating the surface of the copper-deposited layer by placing the polyimide film
5 vertically in a plating solution.